



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	SIO, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	13
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	384 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-LSSOP (0.173", 4.40mm Width)
Supplier Device Package	20-LSSOP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21181sp-u0

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

1.2 Performance Overview

Table 1.1 outlines the Functions and Specifications for R8C/18 Group and Table 1.2 outlines the Functions and Specifications for R8C/19 Group.

	Item	Specification		
CPU	Number of fundamental	89 instructions		
	instructions			
	Minimum instruction execution	50 ns (f(XIN) = 20 MHz, VCC = 3.0 to 5.5 V)		
	time	100 ns (f(XIN) = 10 MHz, VCC = 2.7 to 5.5 V)		
	Operation mode	Single-chip		
	Address space	1 Mbyte		
	Memory capacity	Refer to Table 1.3 Product Information for R8C/18		
		Group		
Peripheral	Ports	I/O ports: 13 pins (including LED drive port)		
Functions		Input port: 3 pins		
	LED drive ports	I/O ports: 4 pins		
	Timers	Timer X: 8 bits x 1 channel, timer Z: 8 bits x 1 channel		
		(Each timer equipped with 8-bit prescaler)		
		Timer C: 16 bits × 1 channel		
		(Input capture and output compare circuits)		
	Serial interfaces	1 channel		
		Clock synchronous serial I/O, UART		
		1 channel		
		UART		
	Comparator	1-bit comparator: 1 circuit, 4 channels		
	Watchdog timer	15 bits × 1 channel (with prescaler)		
		Reset start selectable, count source protection m		
	Interrupts	Internal: 10 sources, External: 4 sources, Software: 4		
		sources,		
		Priority levels: 7 levels		
	Clock generation circuits	2 circuits		
		Main clock oscillation circuit (with on-chip feedback		
		resistor)		
		 On-chip oscillator (high speed, low speed) 		
		High-speed on-chip oscillator has frequency		
		adjustment function		
	Oscillation stop detection	Main clock oscillation stop detection function		
	function			
	Voltage detection circuit	On-chip		
<u> </u>	Power-on reset circuit	On-chip		
Electric	Supply voltage	VCC = 3.0 to 5.5 V (f(XIN) = 20 MHz)		
Characteristics		VCC = 2.7 to 5.5 V (f(XIN) = 10 MHz)		
	Current consumption	Typ. 9 mA (VCC = 5.0 V, f(XIN) = 20 MHz, comparator stopped)		
		Typ. 5 mA (VCC = 3.0V, f(XIN) = 10 MHz, comparator stopped)		
		Typ. 35 μ A (VCC = 3.0 V, wait mode, peripheral clock off)		
		Typ. 0.7 μA (VCC = 3.0 V, stop mode)		
Flash Memory	Programming and erasure voltage	VCC = 2.7 to 5.5 V		
	Programming and erasure	100 times		
	endurance			
Operating Ambi	ent Temperature	-20 to 85°C		
<u> </u>		-40 to 85°C (D version)		
Package		20-pin molded-plastic LSSOP		
		20-pin molded-plastic SDIP		
		28-pin molded-plastic HWQFN		

 Table 1.1
 Functions and Specifications for R8C/18 Group



CPU	Item Number of fundamental	Specification 89 instructions
CPU		
	instructions Minimum instruction	$E0 = \frac{(f(X N))}{20} = \frac{20}{N} \frac{1}{20} = \frac{1}{20} \frac{1}{100} $
	Minimum instruction	50 ns (f(XIN) = 20 MHz, VCC = 3.0 to 5.5 V) 100 ns (f(XIN) = 40 MHz, VCC = 3.7 to 5.5 V)
	execution time	100 ns (f(XIN) = 10 MHz, VCC = 2.7 to 5.5 V)
	Operation mode Address space	Single-chip
	Memory capacity	1 Mbyte Refer to Table 1.4 Product Information for R8C/19
	Memory capacity	Group
Peripheral	Ports	I/O ports: 13 pins (including LED drive port)
Functions		Input port: 3 pins
T unctions	LED drive ports	I/O ports: 4 pins
	Timers	Timer X: 8 bits × 1 channel, timer Z: 8 bits × 1 channel
		(Each timer equipped with 8-bit prescaler)
		Timer C: 16 bits × 1 channel
		(Input capture and output compare circuits)
	Serial interfaces	1 channel
	Ochar Internaces	Clock synchronous serial I/O, UART
		1 channel
		UART
	Comparator	1-bit comparator: 1 circuit, 4 channels
	Watchdog timer	15 bits × 1 channel (with prescaler)
		Reset start selectable, count source protection mode
	Interrupts	Internal: 10 sources, External: 4 sources, Software: 4
	Interrupts	
		sources, Priority levels: 7 levels
	Clock generation circuits	2 circuits
	Clock generation circuits	Main clock generation circuit (with on-chip feedback
		resistor)
		• On-chip oscillator (high speed, low speed)
		High-speed on-chip oscillator has frequency
		adjustment function
	Oscillation stop detection	Main clock oscillation stop detection function
	function	On this
	Voltage detection circuit	On-chip
Flootrio	Power-on reset circuit	On-chip VCC = 3.0 to 5.5 V (f(XIN) = 20 MHz)
Electric Characteristics	Supply voltage	
Characteristics	Current consumption	VCC = 2.7 to 5.5 V ($f(XIN) = 10 \text{ MHz}$) Typ. 9 mA (VCC = 5.0 V, $f(XIN) = 20 \text{ MHz}$, comparator stopped)
	Current consumption	
		Typ. 5 mA (VCC = 3.0 V , f(XIN) = 10MHz , comparator stopped)
		Typ. 35 μ A (VCC = 3.0 V, wait mode, peripheral clock off)
	Dream ming and area weltage	Typ. 0.7 μA (VCC = 3.0 V, stop mode) VCC = 2.7 to 5.5 V
Flash Memory	Programming and erasure voltage Programming and erasure	10,000 times (data flash)
		1,000 times (program ROM)
Operating Amb	endurance ent Temperature	-20 to 85°C
		-40 to 85°C (D version)
Package		20 pin molded plastic LSSOD
Package		20-pin molded-plastic LSSOP 20-pin molded-plastic SDIP

 Table 1.2
 Functions and Specifications for R8C/19 Group

Current of Apr. 2006

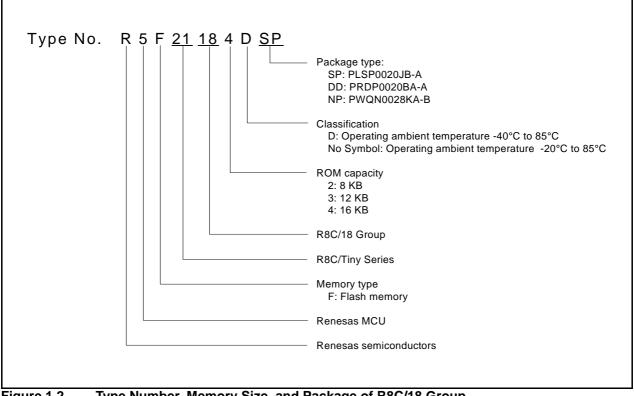
1.4 **Product Information**

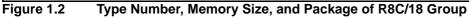
Table 1.3 lists Product Information for R8C/18 Group and Table 1.4 lists Product Information for R8C/19 Group.

Type No.	ROM Capacity	RAM Capacity	Package Type	Remarks
R5F21181SP	4 Kbytes	384 bytes	PLSP0020JB-A	Flash memory version
R5F21182SP	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F21183SP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F21184SP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F21181DSP (D)	4 Kbytes	384 bytes	PLSP0020JB-A	D version
R5F21182DSP (D)	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F21183DSP (D)	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F21184DSP (D)	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F21181DD	4 Kbytes	384 bytes	PRDP0020BA-A	Flash memory version
R5F21182DD	8 Kbytes	512 bytes	PRDP0020BA-A	
R5F21183DD	12 Kbytes	768 bytes	PRDP0020BA-A	
R5F21184DD	16 Kbytes	1 Kbyte	PRDP0020BA-A	
R5F21182NP	8 Kbytes	512 bytes	PWQN0028KA-B	Flash memory version
R5F21183NP	12 Kbytes	768 bytes	PWQN0028KA-B	
R5F21184NP	16 Kbytes	1 Kbyte	PWQN0028KA-B	

Table 1.3 **Product Information for R8C/18 Group**

(D): Under Development







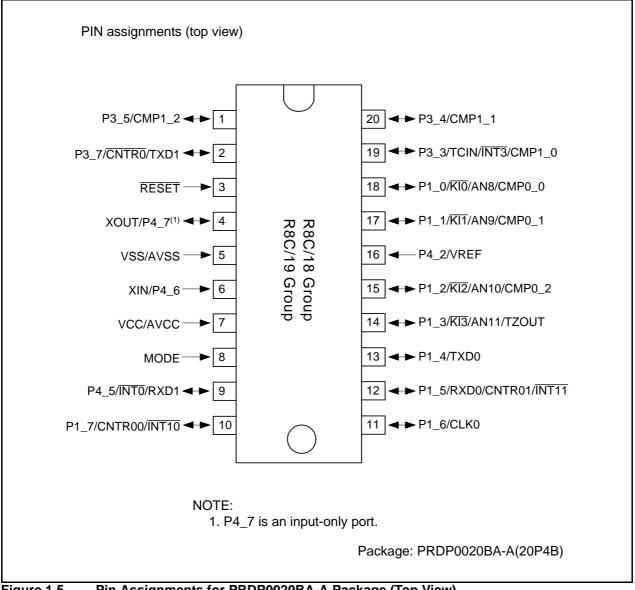


Figure 1.5 Pin Assignments for PRDP0020BA-A Package (Top View)

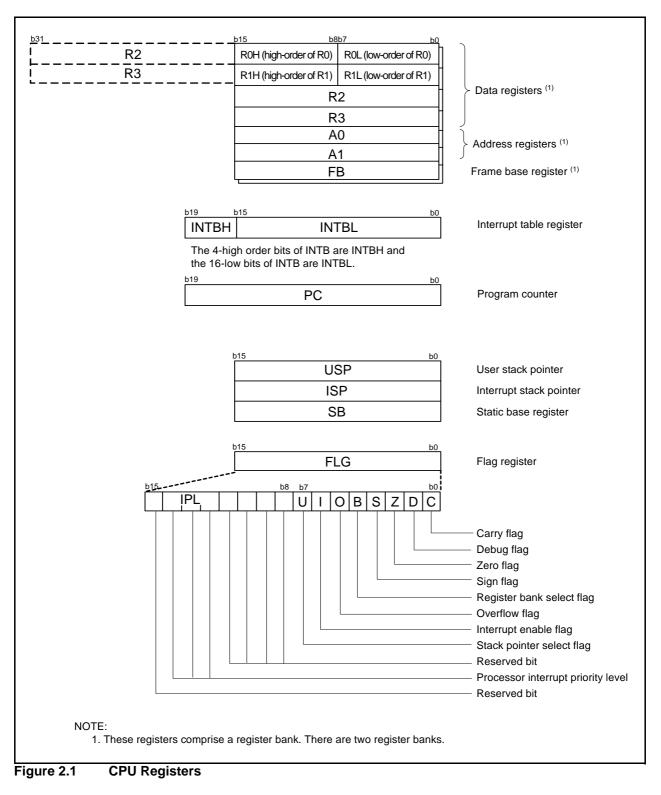


Pin	Control	Port	I/C	I/O Pin Functions for Peripheral Modules			
Number	Pin	Full	Interrupt	Timer	Serial Interface	Comparator	
1		P3_5		CMP1_2			
2		P3_7		CNTR0	TXD1		
3	RESET						
4	XOUT	P4_7					
5	VSS/AVSS						
6	XIN	P4_6					
7	VCC/AVCC						
8	MODE						
9		P4_5	INTO		RXD1		
10		P1_7	INT10	CNTR00			
11		P1_6			CLK0		
12		P1_5	INT11	CNTR01	RXD0		
13		P1_4			TXD0		
14		P1_3	KI3	TZOUT		AN11	
15		P1_2	KI2	CMP0_2		AN10	
16	VREF	P4_2					
17		P1_1	KI1	CMP0_1		AN9	
18		P1_0	KI0	CMP0_0		AN8	
19		P3_3	INT3	TCIN/CMP1_0			
20		P3_4		CMP1_1			

Table 1.6 Pin Name Information by Pin Number of PLSP0020JB-A, PRDP0020BA-A packages

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.



3. Memory

3. Memory

3.1 R8C/18 Group

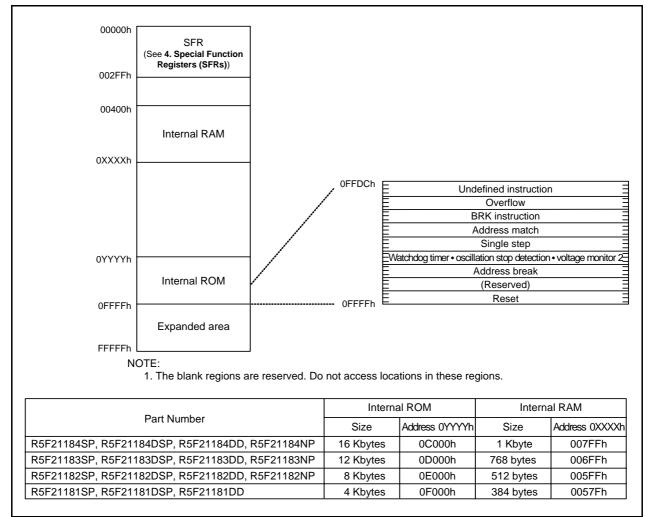
Figure 3.1 is a Memory Map of R8C/18 Group. The R8C/18 Group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM area is allocated lower addresses, beginning with address 0FFFFh. For example, a 16-Kbyte internal ROM is allocated addresses 0C000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 1-Kbyte internal RAM area is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.





4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.4 list the special function registers.

Table 4.1SFR Information (1)(1)

Address	Pagiatar	Symbol	After reset
	Register	Symbol	Allei Tesei
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	0010000b
0008h		0	
0009h	Address Match Interrupt Enable Register	AIER	00h
0003h	Protect Register	PRCR	00h
000An		FRUK	0011
		0.00	000004001
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00011111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			X0h
0013h		1	
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h	4		X0h
0017h			7.011
0017h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h
001Dh			
001Eh	INT0 Input Filter Select Register	INTOF	00h
001Fh			
0020h	High-Speed On-Chip Oscillator Control Register 0	HRA0	00h
0021h	High-Speed On-Chip Oscillator Control Register 1	HRA1	When shipping
0022h	High-Speed On-Chip Oscillator Control Register 2	HRA2	00h
0023h		1110.02	0011
002011			
002Ah			
002Bh			
002Ch			
002Dh			
002Eh			
002Fh			
0030h			
0031h	Voltage Detection Register 1 ⁽²⁾	VCA1	00001000b
0032h	Voltage Detection Register 2 ⁽²⁾	VCA2	00h(3)
-			0100000b ⁽⁴⁾
0033h			010000000,7
		+	
0034h		ļ	
0035h		10040	
0036h	Voltage Monitor 1 Circuit Control Register ⁽²⁾	VW1C	0000X000b ⁽³⁾
			0100X001b ⁽⁴⁾
0037h	Voltage Monitor 2 Circuit Control Register ⁽⁵⁾	VW2C	00h
0038h		1	
0039h			
003Ah		+	
003Bh		+	
003Dh			
003Ch		+	
		ļ	
003Eh			
003Fh			

X: Undefined

NOTES:

- 1. The blank regions are reserved. Do not access locations in these regions.
- 2. Software reset, watchdog timer reset, and voltage monitor 2 reset do not affect this register.

3. After hardware reset.

- 4. After power-on reset or voltage monitor 1 reset.
- 5. Software reset, watchdog timer reset, and voltage monitor 2 reset do not affect b2 and b3.

		-	
Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h			
0048h			
0049h			
004Ah			
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	Comparator Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh			
0050h	Compare 1 Interrupt Control Register	CMP1IC	XXXXX000b
0051h	UART0 Transmit Interrupt Control Register	SOTIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	SORIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h			
0056h	Timer X Interrupt Control Register	TXIC	XXXXX000b
0050h			
0057h	Timer Z Interrupt Control Register	TZIC	XXXXX000b
0059h	·	INT1IC	XXXXX000b
	INT1 Interrupt Control Register		
005Ah	INT3 Interrupt Control Register	INT3IC	XXXXX000b
005Bh	Timer C Interrupt Control Register	TCIC	XXXXX000b
005Ch	Compare 0 Interrupt Control Register	CMP0IC	XXXXX000b
005Dh	INT0 Interrupt Control Register	INTOIC	XX00X000b
005Eh			
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah	<u> </u>		
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			
	L		

Table 4.2SFR Information (2)⁽¹⁾

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Addroop	Pagintar	Symbol	After react
Address 00C0h	Register A/D Register	AD	After reset XXh
00C011		AD	~~!!
00C2h			-
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h 00D2h			
00D2h 00D3h			
00D3h 00D4h	A/D Control Register 2	ADCON2	00h
00D4n		, 10001N2	0011
00D6h	A/D Control Register 0	ADCON0	00000XXXb
00D7h	A/D Control Register 1	ADCON1	00000000000000000000000000000000000000
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h		.	× × ×
00E1h	Port P1 Register	P1	XXh
00E2h	Dest D4 Dissettion De sigter	004	0.0h
00E3h 00E4h	Port P1 Direction Register	PD1	00h
00E4h	Port P3 Register	P3	XXh
00E6h	Forregister	гJ	~~!!
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h	· · · · · · · · · · · · · · · · · · ·		
00EAh	Port P4 Direction Register	PD4	00h
00EBh	-		
00ECh			
00EDh			
00EEh			
00EFh			
00F0h			
00F1h			
00F2h			
00F3h 00F4h			
00F4h 00F5h			
00F6h			+
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh	Pull-Up Control Register 0	PUR0	00XX0000b
00FDh	Pull-Up Control Register 1	PUR1	XXXXXX0Xb
00FEh	Port P1 Drive Capacity Control Register	DRR	00h
00FFh	Timer C Output Control Register	TCOUT	00h
01B3h	Flash Memory Control Register 4	FMR4	0100000b
01B4h	Elech Memory Control Desister 4		1000000Xh
01B5h 01B6h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h 01B7h	Flash Memory Control Register 0	FMR0	0000001b
	I IASH METHOLY CUITEUL REGISTER U		00000010
0FFFFh	Optional Function Select Register	OFS	(Note 2)
011111		0.0	(11010 2)

SFR Information (4)⁽¹⁾ Table 4.4

X: Undefined

NOTES:

The blank regions, 0100h to 01B2h and 01B8h to 02FFh are all reserved. Do not access locations in these regions.
 The OFS register cannot be changed by a program. Use a flash programmer to write to it.

Table 5.3	Comparator Characteristics
-----------	-----------------------------------

Symbol	Parameter	Conditions		Unit		
Symbol	Falametei	Conditions		Тур.	Max.	Unit
-	Resolution		-	-	1	Bit
-	Absolute accuracy	$\phi AD = 10 \text{ MHz}^{(3)}$	-	-	±20	mV
tconv	Conversion time	$\phi AD = 10 \text{ MHz}^{(3)}$	1	-	-	μs
Vref	Reference voltage		0	-	AVcc	V
Via	Analog input voltage		0	-	AVcc	V
-	Comparator conversion operating clock frequency ⁽²⁾		1	_	10	MHz

NOTES:

- Vcc = 2.7 to 5.5 V at Topr = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
 If f1 exceeds 10 MHz, divided f1 and ensure the comparator conversion operating clock frequency (\$\phiAD\$) is 10 MHz or below.
- 3. If AVcc is less than 4.2 V, divided f1 and ensure the comparator conversion operating clock frequency (ϕ AD) is f1/2 or below.

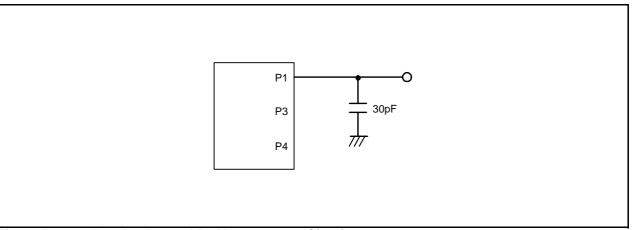


Figure 5.1 Port P1, P3, and P4 Measurement Circuit

Symbol	Parameter	Conditions		Unit		
Symbol	Falameter	Conditions	Min.	Тур.	Max.	Unit
-	Program/erase endurance ⁽²⁾		10,000 ⁽³⁾	-	-	times
_	Byte program time (Program/erase endurance \leq 1,000 times)		-	50	400	μS
_	Byte program time (Program/erase endurance > 1,000 times)		_	65	_	μS
_	Block erase time (Program/erase endurance ≤ 1,000 times)		_	0.2	9	S
-	Block erase time (Program/erase endurance > 1,000 times)		_	0.3	_	S
td(SR-SUS)	Time delay from suspend request until suspend		-	_	97+CPU clock × 6 cycles	μS
-	Interval from erase start/restart until following suspend request		650	_	_	μS
-	Interval from program start/restart until following suspend request		0	-	_	ns
-	Time from suspend until program/erase restart		-	-	3+CPU clock × 4 cycles	μS
-	Program, erase voltage		2.7	-	5.5	V
-	Read voltage		2.7	-	5.5	V
-	Program, erase temperature		-20 ⁽⁸⁾	-	85	°C
-	Data hold time ⁽⁹⁾	Ambient temperature = 55 °C	20	-	-	year

Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics

NOTES:

1. Vcc = 2.7 to 5.5 V at Topr = -20 to 85 $^{\circ}$ C / -40 to 85 $^{\circ}$ C, unless otherwise specified.

2. Definition of programming/erasure endurance

The programming and erasure endurance is defined on a per-block basis. If the programming and erasure endurance is n (n = 100 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one. However, the same address must not be programmed more than once per erase operation (overwriting prohibited).

3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).

- 4. If emergency processing is required, a suspend request can be generated independent of this characteristic. In that case the normal time delay to suspend can be applied to the request. However, we recommend that a suspend request with an interval of less than 650 μs is only used once because, if the suspend state continues, erasure cannot operate and the incidence of erasure error rises.
- 5. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erase count of each block and limit the number of erase operations to a certain number.
- 6. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
- 7. Customers desiring programming/erasure failure rate information should contact their Renesas technical support representative.
- 8. -40 °C for D version.
- 9. The data hold time includes time that the power supply is off or the clock is not supplied.

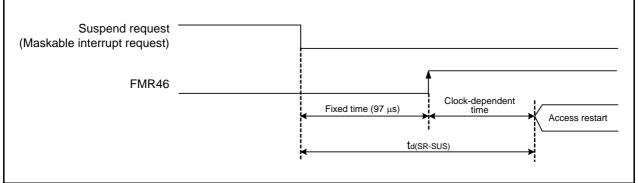


Figure 5.2 Transition Time to Suspend

Symbol	Parameter	Condition	Standard		Unit	
			Min.	Тур.	Max.	
Vpor2	Power-on reset valid voltage	$\text{-}20^\circ C \leq Topr \leq 85^\circ C$	-	-	Vdet1	V
tw(Vpor2-Vdet1)	Supply voltage rising time when power-on reset is deasserted ⁽¹⁾	$\label{eq:constraint} \begin{array}{l} -20^\circ C \leq Topr \leq 85^\circ C, \\ t_{w(por2)} \geq 0s^{(3)} \end{array}$	-	-	100	ms

Table 5.8 Reset Circuit Electrical Characteristics (When Using Voltage Monitor 1 Reset)

NOTES:

1. This condition is not applicable when using with $Vcc \ge 1.0 V$.

2. When turning power on after the time to hold the external power below effective voltage (Vpor1) exceeds10 s, refer to Table 5.9 Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 1 Reset).

3. tw(por2) is the time to hold the external power below effective voltage (Vpor2).

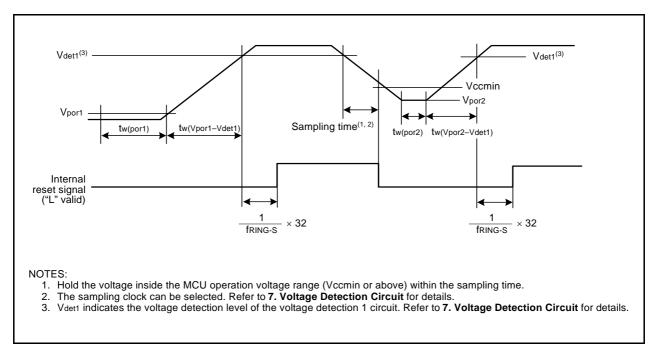
Table 5.9 Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 1 Reset)

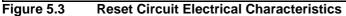
Symbol	Parameter	Condition		Standar	d	Unit	
			Min.	Тур.	Max.		
Vpor1	Power-on reset valid voltage	$-20^\circ C \le Topr \le 85^\circ C$	-	-	0.1	V	
tw(Vpor1-Vdet1)	Supply voltage rising time when power-on reset is deasserted	$\begin{array}{l} 0^{\circ}C \leq Topr \leq 85^{\circ}C, \\ tw(por1) \geq 10 \ s^{(2)} \end{array}$	-	-	100	ms	
tw(Vpor1-Vdet1)	Supply voltage rising time when power-on reset is deasserted	$\label{eq:constraint} \begin{array}{l} -20^\circ C \leq \mbox{Topr} < 0^\circ C, \\ \mbox{tw(por1)} \geq 30 \ s^{(2)} \end{array}$	-	-	100	ms	
tw(Vpor1-Vdet1)	Supply voltage rising time when power-on reset is deasserted	$\label{eq:constraint} \begin{array}{l} -20^\circ C \leq Topr < 0^\circ C, \\ tw(por1) \geq 10 \ s^{(2)} \end{array}$	-	-	1	ms	
tw(Vpor1-Vdet1)	Supply voltage rising time when power-on reset is deasserted	$\label{eq:constraint} \begin{split} 0^\circ C &\leq Topr \leq 85^\circ C, \\ t_{w(por1)} \geq 1 \ s^{(2)} \end{split}$	-	-	0.5	ms	

NOTES:

1. When not using voltage monitor 1, use with Vcc \ge 2.7 V.

2. tw(por1) is the time to hold the external power below effective voltage (Vpor1).





Symbol	Parameter	Condition		Standard		
Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
_	High-speed on-chip oscillator frequency when the reset is deasserted	Vcc = 5.0 V, Topr = 25 °C	-	8	-	MHz
-	High-speed on-chip oscillator frequency temperature	0 to +60 °C/5 V ± 5 % ⁽³⁾	7.76	-	8.24	MHz
	supply voltage dependence ⁽²⁾	-20 to +85 °C/2.7 to 5.5 V ⁽³⁾	7.68	-	8.32	MHz
		-40 to +85 °C/2.7 to 5.5 V ⁽³⁾	7.44	-	8.32	MHz

Table 5.10 High-speed On-Chip Oscillator Circuit Electrical Characteristics

NOTES:

1. The measurement condition is Vcc = 5.0 V and Topr = 25 °C.

2. Refer to 10.6.4 High-Speed On-Chip Oscillator Clock for notes on high-speed on-chip oscillator clock.

3. The standard value shows when the HRA1 register is assumed as the value in shipping and the HRA2 register value is set to 00h.

Table 5.11 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
Symbol	Falanetei	Condition	Min.	Тур.	Max.	Offic
td(P-R)	Time for internal power supply stabilization during power-on ⁽²⁾		1	-	2000	μS
td(R-S)	STOP exit time ⁽³⁾		-	-	150	μS

NOTES:

1. The measurement condition is Vcc = 2.7 to 5.5 V and Topr = 25 °C.

2. Waiting time until the internal power supply generation circuit stabilizes during power-on.

3. Time until CPU clock supply starts after the interrupt is acknowledged to exit stop mode.

Symbol	Parameter	Condition		Standard			Unit
-,				Min.	Тур.	Max.	
lcc	Power supply current (Vcc = 2.7 to 3.3 V) Single-chip mode, output pins are open,	High-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	8	13	mA
other pins are Vss, comparator is stopped			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	-	7	12	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	_	5	_	mA
		Medium- speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	3	_	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	2.5	-	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	1.6	_	mA
		High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz No division	_	3.5	7.5	mA
			Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	_	1.5	_	mA
		Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8 FMR47 = 1	-	100	280	μA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = 0	_	37	74	μΑ
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = 0		35	70	μΑ
		Stop mode	Main clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = 0	_	0.7	3.0	μΑ

Table 5.20 Electrical Characteristics (4) [Vcc = 3V] (Topr = -40 to 85 °C, unless otherwise specified.)

Table 5.24 Serial Interface

Symbol	Parameter		dard	Unit
	Parameter	Min.	Max.	Unit
tc(CK)	CLKi input cycle time	300	-	ns
tw(CKH)	CLKi input "H" width	150	-	ns
tW(CKL)	CLKi input "L" width	150	-	ns
td(C-Q)	TXDi output delay time	-	80	ns
th(C-Q)	TXDi hold time	0	-	ns
tsu(D-C)	RXDi input setup time	70	-	ns
th(C-D)	RXDi input hold time	90	-	ns

i = 0 or 1

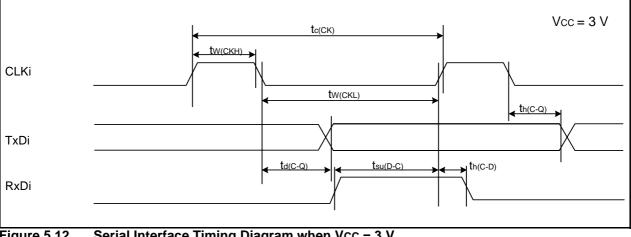


Figure 5.12 Serial Interface Timing Diagram when Vcc = 3 V

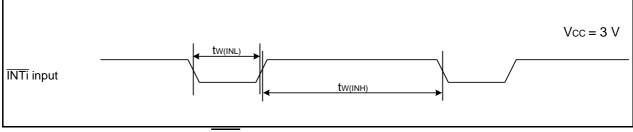
Table 5.25 External Interrupt INT0 Input

Symbol	Parameter	Stan	dard	Unit
Symbol	Falameter	Min. Max.	Onit	
tw(INH)	INT0 input "H" width	380 ⁽¹⁾	-	ns
tw(INL)	INTO input "L" width	380(2)	I	ns

NOTES:

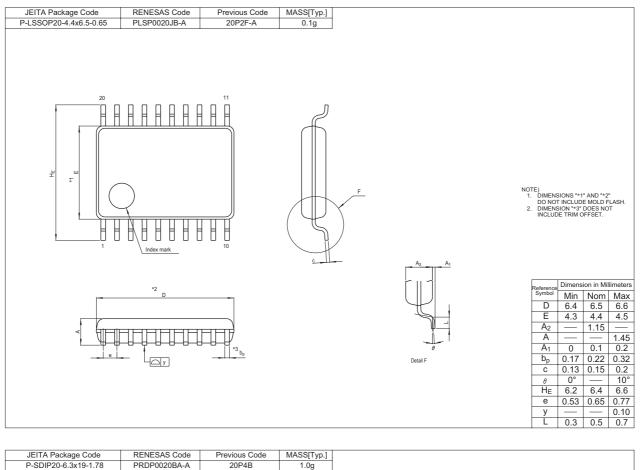
1. When selecting the digital filter by the INTO input filter select bit, use an INTO input HIGH width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater.

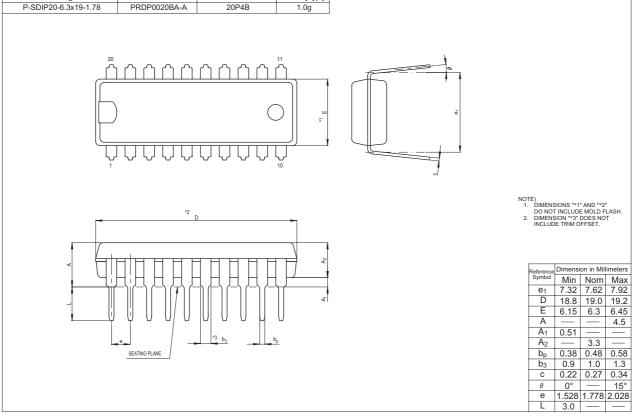
2. When selecting the digital filter by the INTO input filter select bit, use an INTO input LOW width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater.

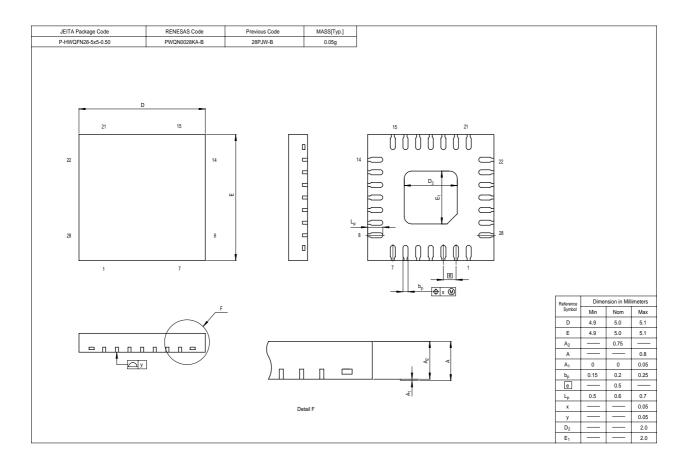


External Interrupt INTO Input Timing Diagram when Vcc = 3 V Figure 5.13

Package Dimensions







REVISION HISTORY

R8C/18 Group, R8C/19 Group Datasheet

Davi	Dete		Description
Rev.	Date	Page	Summary
0.10	Nov 15, 2004	-	First Edition issued
0.20	Jan 11, 2005	5, 6	Tables 1.3 and 1.4: The date updated
0.21	Apr 04, 2005	2, 3	Tables 1.1 and 1.2: Partly revised
		4	Figure 1.1: Partly revised
		5, 6	Tables 1.3 and 1.4: Partly revised
		5, 6	Figure 1.2 and 1.3: Partly revised
		7, 8	Figure 1.4 and 1.5: Partly revised
		10	Table 1.6: Partly revised
		16	Table 4.1: Partly revised
		17	Table 4.2: Partly revised
		18	Table 4.3: Partly revised
		20	Package Dimensions are revised
1.00	May 27, 2005	5, 6	Tables 1.3 and 1.4: Partly revised
		9	Table 1.5: Partly revised
		25	Table 5.9: Revised
		26	Table 5.10: Partly revised
		28	Table 5.13: Partly revised
		32	Table 5.20: Partly revised
1.10	Jun 09, 2005	26	Table 5.10: Partly revised
1.20	Nov 01, 2005	3	Table 1.2 Performance Outline of the R8C/19 Group;Flash Memory: (Data area) \rightarrow (Data flash)(Program area) \rightarrow (Program ROM) revised
		4	Figure 1.1 Block Diagram; "Peripheral Function" added, "System Clock Generation" → "System Clock Generator" revised
		6	Table 1.4 Product Information of R8C/19 Group; ROM capacity: "Program area" \rightarrow "Program ROM", "Data area" \rightarrow "Data flash" revised
		9	Table 1.5 Pin Description; Power Supply Input: "VCC/AVCC" → "VCC", "VSS/AVSS" → "VSS" revised Analog Power Supply Input: added
		11	Figure 2.1 CPU Register; "Reserved Area" → "Reserved Bit" revised
		13	2.8.10 Reserved Area; "Reserved Area" → "Reserved Bit" revised
		15	3.2 R8C/19 Group, Figure 3.2 Memory Map of R8C/19 Group; "Data area" \rightarrow "Data flash", "Program area" \rightarrow "Program ROM" revised

F	REVISION H	ISTOF	RY R8C/18 Group, R8C/19 Group Datasheet
Rev. Date			Description
Rev.	Date	Page	Summary
1.20	Nov 01, 2005	16	Table 4.1 SFR Information(1);0009h: "XXXXX00b" \rightarrow "00h"000Ah: "00XXX000b" \rightarrow "00h"001Eh: "XXXXX000b" \rightarrow "00h" revised
		18	Table 4.3 SFR Information(3);0085h:"Prescaler Z" \rightarrow "Prescaler Z Register"0086h:"Timer Z Secondary" \rightarrow "Timer Z Secondary Register"0087h:"Timer Z Primary" \rightarrow "Timer Z Primary Register"008Ch:"Prescaler X" \rightarrow "Prescaler X Register"008Dh:"Timer X" \rightarrow "Timer X Register"0090h, 0091h:"Timer C" \rightarrow "Timer C Register" revised
		22	Table 5.4 Flash Memory (Program ROM) Electrical Characteristics; NOTES 3 and 5 revised, NOTE8 deleted
		23	Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics; NOTES 1 and 3 revised
		25	Table 5.8 Reset Circuit Electrical Characteristics (When Using VoltageMonitor 1 Reset); NOTE 2 revised
		26	 Table 5.10 High-speed On-Chip Oscillator Circuit Electrical Characteristics; "High-Speed On-Chip Oscillator" → "High-Speed On-Chip Oscillator Frequency" revised NOTE 2, 3 added
		28	Table 5.13 Electrical Characteristics (2) [Vcc = 5V]; NOTE 1 deleted
		32	Table 5.20 Electrical Characteristics (4) [Vcc = 3V]; NOTE 1 deleted
1.30	Dec 16, 2005	_	Products of PWQN0028KA-B package included
		5, 6	Table 1.3, Table 1.4 revised
		24	Table 5.4 Flash Memory (Program ROM) Electrical Characteristics; Ta \rightarrow Ambient temperature
		25	Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics; Ta \rightarrow Ambient temperature
		30, 34	Table 5.13, Table 5.20; The title revised, Condition of Stop Mode added
		32, 36	Table 5.17, Table 5.24; td(C-Q) and tsu(D-C) revised
		37, 38	Package Dimensions revised
1.40	Apr 14, 2006	2, 3	Table 1.1, Table 1.2; Interrupts: Internal 8 \rightarrow 10 sources,
		5, 6	Table 1.3, Table 1.4; Type No. added, deleted
		16, 17	Figure 3.1, Figure 3.2; Part Number added, deleted
		24, 25	Table 5.4, Table 5.5;
			Conditions: VCC = 5.0 V at Topr = $25 \degree \text{C}$ deleted